

Technical Data Sheet

MODEL NO: 117UR/ANG/ANB2 1204 Package 3.2*1.0*1.3mm Chip LEDs

Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Red	
InGaN	Green	White diffused lens
InGaN	Blue	

Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

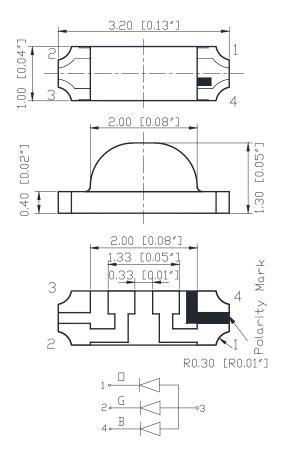
Parameter		Test	Symbol	Value			Unit
		Condition		Min	Тур	Max	Unit
Spectral half bandwidth	Red				21		
	Green	IF=20mA	Δλ		34		nm
	Blue				27		
Dominant wavelength	Red	IF=20mA		615	620	630	
	Green		λD	550	525	535	nm
	Blue			465	470	475	
Forward voltage	Red	IF=20mA		1.7	2.0	2.5	
	Green		VF	2.8	3.2	3.7	V
	Blue			2.8	3.1	3.7	
Luminous intensity	Red	IF=20mA		100	190	320	
	Green		lv	320	530	1000	mcd
	Blue			63	110	200	
Viewing angle at 50% lv		IF=10mA	2 <i>0</i> 1/2		150		Deg
Reverse current		V _R =5V	lr			10	μА

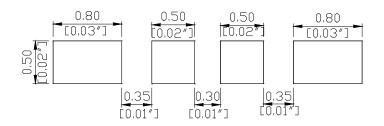


Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value			Unit
		R	G	В	
Power dissipation	Pd	75	111	111	mW
Forward current	lF	30			mA
Reverse voltage	VR	5			V
Operating temperature range	Тор	-40 ~+80			$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85			$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	lfp	125			mA

PACKAGING DIMENSIONS (mm):



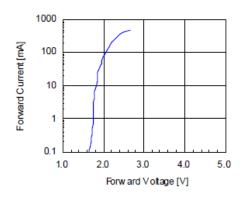


NOTES:

- 1. All dimensions are in millimeters (inches); 2. Tolerances are ± 0.1 mm (0.004inch) unless otherwise noted.



Typical Electro-Optical Characteristics Curve:Red



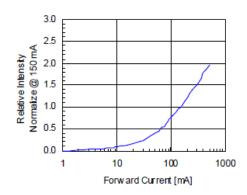


Fig 3. Forward Voltage vs. Temperature

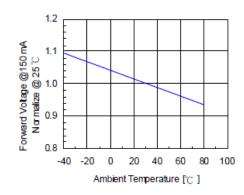


Fig 4. Relative Intensity vs. Temperature

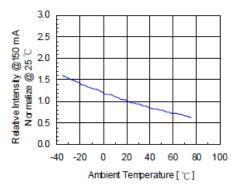
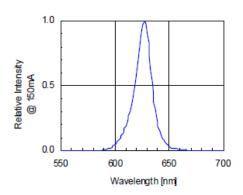


Fig 5. Relative Intensity vs. Wavelength





Typical Electro-Optical Characteristics Curve: Green

Fig 1. Forward Current vs. Forward Voltage

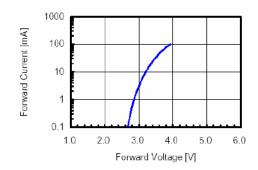


Fig 3. Forward Voltage vs. Temperature

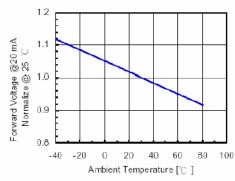


Fig 5.Relative Intensity vs. Wavelength

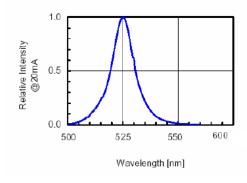


Fig 2. Relative Intensity vs. Forward Current

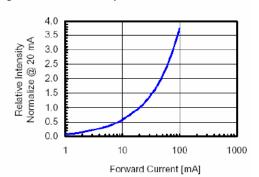
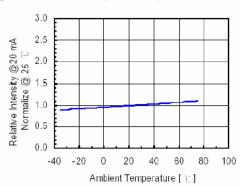


Fig 4. Relative Intensity vs. Temperature





Typical Electro-Optical Characteristics Curve: Blue

Fig 1. Forward Current vs. Forward Voltage

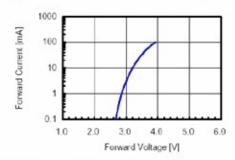


Fig 3. Forward Voltage vs. Temperature

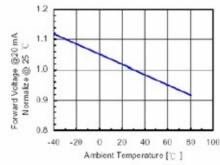


Fig 5.Relative Intensity vs. Wavelength

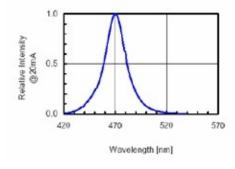


Fig 2. Relative Intensity vs. Forward Current

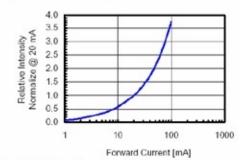
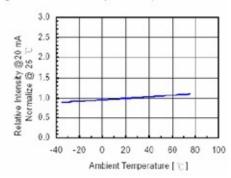


Fig 4. Relative Intensity vs. Temperature



Precautions For Use:

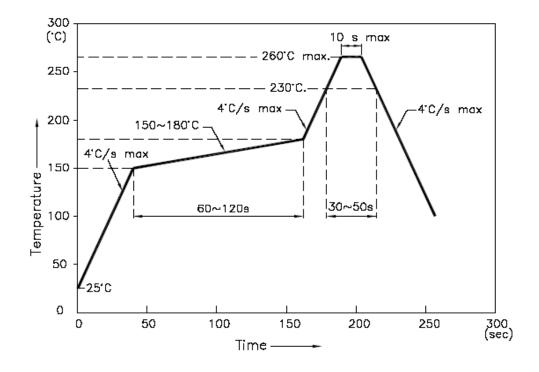
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C \sim 30 $^{\circ}$ C, 60 $^{\circ}$ R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}\mathbb{C}(\pm 5^{\circ}\mathbb{C})$.the maximum soldering temperature should be limited to $260^{\circ}\mathbb{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

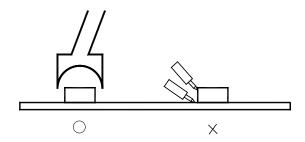


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

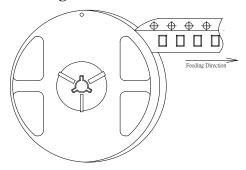
- 1. Customer must finish rework within 5 sec under 260° C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



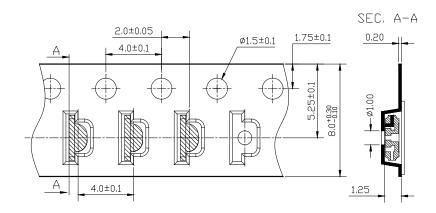
■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.



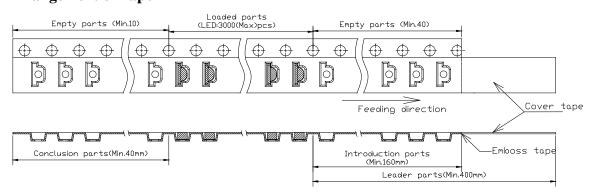
■Feeding Direction



■Dimensions of Tape (Unit: mm)



■Arrangement of Tape



■Note

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. 3,000 pcs/Reel
- 4. Packing will be multiple of 500, e.g 500pcs/R, 1000pcs/R, 1500pcs/R..etc , MAX 3000pcs/R